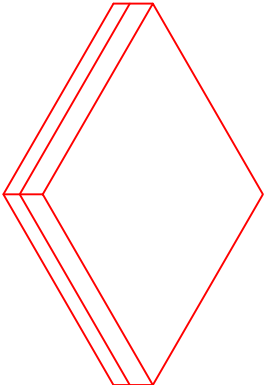


REV.	DESCRIPTION	DATE	CHECKED	GENERATED BY
00	INITIAL RELEASE PER DCN# C02894	01/14/98	E.B.	JBW
01	UPDATED TO STANDARDS, DCN C04486	06/28/98	E.B.	HLE

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7. REFERENCE SPECIFICATIONS:
A. LAWT SPEC #001-0531-2234: PACKING, OPERATION PROCEDURE.
B. LAWT SPEC #001-0519-2062: MARKING.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BOWFS IS 36.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 6 X 6.
2. THE BASIC SOLDER BOWP GRID PITCH IS 0.90.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS			PROJECTION		APPROVALS		DATE		TITLE		DATE		SCALE		SHEET 1 OF 3	
DECIMAL, X.X ±0.10 X.XX ±0.05 X.XXX ±0.03			ANGULAR ±1°		DRAWN I. WESLEY		01/06/98		PACKAGE OUTLINE - CABGA 36, 6.00mm X 6.00mm, 2 LAYER, 0.80mm PITCH, LAMINATE SUBSTRATE, AAP		01/06/98		73291		01	
MATERIAL N/A			CHECKED D. GASTELLONE		DATE 01/06/98		01/06/98		0.80mm PITCH, LAMINATE SUBSTRATE, AAP		01/06/98		73291		01	
FINISH N/A			INSPECTED T. PANCIKAK		DATE 01/06/98		01/06/98		0.80mm PITCH, LAMINATE SUBSTRATE, AAP		01/06/98		73291		01	
DO NOT SCALE DRAWING			APPROVED M. ANTONIO		DATE 01/14/98		01/14/98		0.80mm PITCH, LAMINATE SUBSTRATE, AAP		01/14/98		73291		01	

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